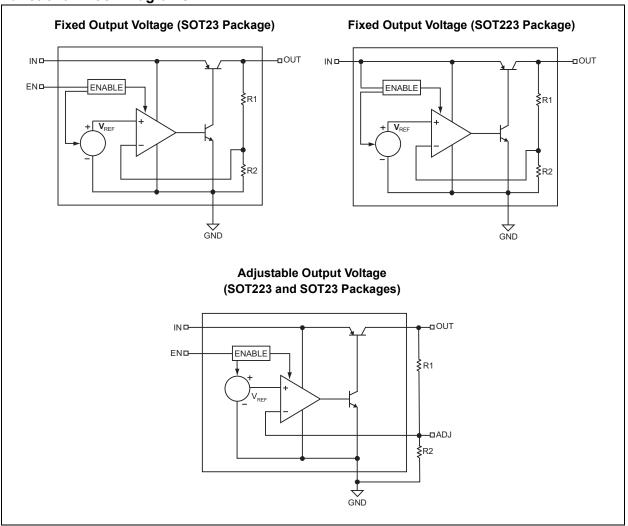
Package Types



Functional Block Diagrams



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Operating Ratings‡

- † **Notice:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability. Specifications are for packaged product only.
- **‡** The device is not ensured to function outside its operating ratings.

Note 1: Devices are ESD sensitive. Handling precautions are recommended.

TABLE 1-1: ELECTRICAL CHARACTERISTICS

Electrical Characteristics: T = 125°C with \/ =\/ 11//.1

Electrical Characteristics: $T_J = +25^{\circ}C$ with $V_{IN} = V_{OUT} + 1V$; $I_{OUT} = 100 \ \mu\text{A}$; Bold values indicate $-40^{\circ}C \le T_J \le +125^{\circ}C$, unless otherwise specified. Specifications for packaged product only.							
Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions	
Output Voltage Accuracy	V _{OUT}	-1.0	_	1.0	%	Variation from naminal V	
		-2.0	_	2.0	70	Variation from nominal V _{OUT}	
Line Regulation	$\Delta V_{OUT}/\Delta V_{IN}$		0.04	0.5	%	$V_{IN} = V_{OUT} + 1V \text{ to } 36V$	
Load Regulation	$\Delta V_{OUT}/V_{OUT}$	_	0.25	1	%	I _{OUT} = 100 μA to 100 mA	
Dropout Voltage	V_{DO}	_	50	_		I _{OUT} = 100 μA	
		_	230	300		1 50 mA	
		_	_	400	mV	I _{OUT} = 50 mA	
			270	400		- 100 mA	
			_	450		I _{OUT} = 100 mA	
Ground Current	I_{GND}		18	30	μA	I _{OUT} = 100 μA	
			_	35	μΛ		
			0.25	0.70	mA	I _{OUT} = 50 mA	
		_	1	2	ША	I _{OUT} = 100 mA	
Ground Current in Shutdown	I _{SHDN}	_	0.1	1	μA	$V_{EN} \le 0.6V$; $V_{IN} = 36V$ (SOT23 package only)	
Short-Circuit Current	I _{SC}	_	190	350	mA	V _{OUT} = 0V	
Output Leakage, Reverse Polarity Input (Note 2)	V _{OUT}	_	-0.1	_	V	Load = 500Ω; V _{IN} = –15V	
Enable Input (SOT23 Packa	ige Only)						
Input Low Voltage	V		_	0.6	V	Regulator off	
Input High Voltage	V _{EN}	2.0	_	_	V	Regulator on	
Enable Input Current	I _{EN}	-1.0	0.01	1.0		V _{EN} = 0.6V; regulator off	
		_	0.1	1.0	μA	V _{EN} = 2.0V; regulator on	
		_	0.5	2.5		V _{EN} = 36V; regulator on	
Start-up Time	t _{START}	_	1.7	7	ms	V _{IN} applied before EN signal	

- Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e., T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +125°C rating. Sustained junction temperatures above +125°C can impact the device reliability.
 - 2: Design guidance only, not production tested.

= 100 uA: Pald values indicate 40°C < T < 1125°C

TEMPERATURE SPECIFICATIONS(1)

Parameters		Min.	Тур.	Max.	Units	Conditions
Temperature Ranges						
Junction Operating Temperature Range	TJ	-40	_	+125	°C	_
Storage Temperature Range		-65	_	+150	°C	_
Package Thermal Resistances						
Thermal Resistance 5-Lead SOT23		_	235	_	°C/W	_
Thermal Resistance 3-Lead SOT223		_	50	_	°C/W	_

- Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e., T_A , T_J , θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +125°C rating. Sustained junction temperatures above +125°C can impact the device reliability.
 - 2: Design guidance only, not production tested.

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

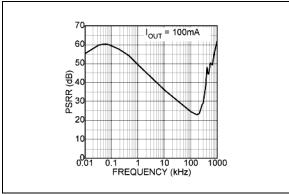


FIGURE 2-1: Power Supply Rejection Ratio.

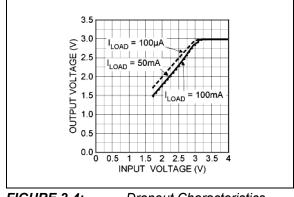


FIGURE 2-4: Dropout Characteristics.

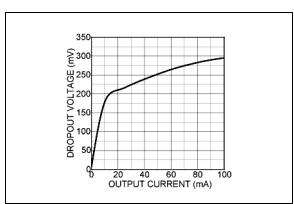
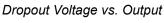


FIGURE 2-2: Current.



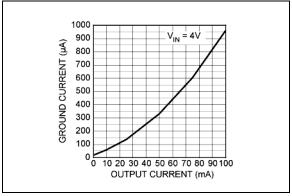


FIGURE 2-5: Ground Pin Current vs. Output Current.

16

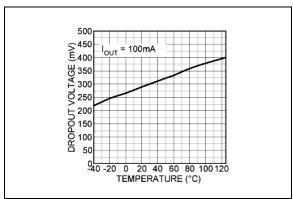
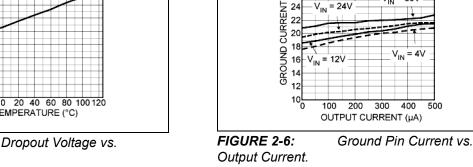


FIGURE 2-3: Temperature.



V_{IN} = 36V

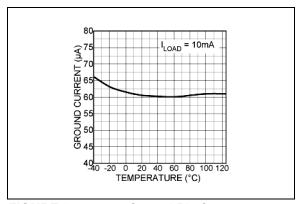


FIGURE 2-7: Temperature.

Ground Pin Current vs.

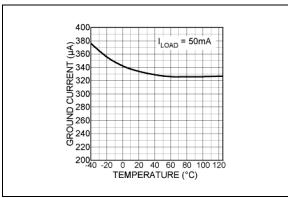


FIGURE 2-8: Temperature.

Ground Pin Current vs.

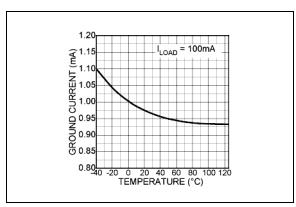


FIGURE 2-9: Temperature.

Ground Pin Current vs.

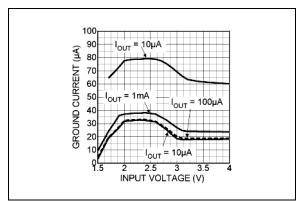


FIGURE 2-10: Input Voltage.

Ground Pin Current vs.

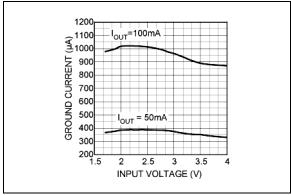


FIGURE 2-11: Input Voltage.

Ground Pin Current vs.

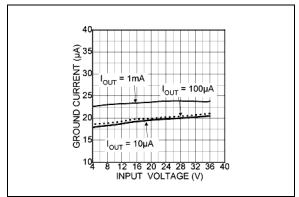


FIGURE 2-12: Input Voltage.

Ground Pin Current vs.

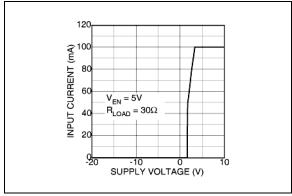


FIGURE 2-13: Voltage.

Input Current vs. Supply

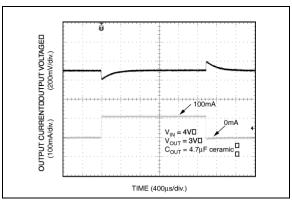


FIGURE 2-16:

Load Transient Response.

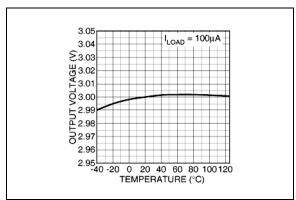


FIGURE 2-14: Temperature.

Output Voltage vs.

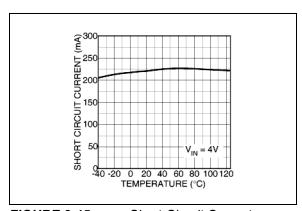


FIGURE 2-15:

Short-Circuit Current vs.

Temperature.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

Pin Number SOT223	Pin Number SOT23	Pin Name	Description
1	1	IN	Supply Input.
2	2	GND	Ground.
_	3	EN	Enable (Input). Logic Low = Shutdown; Logic High = Enable.
_	4	NC	No Connect.
		ADJ	Adjustable (Input). Feedback Input; Connect to Resistive Voltage Divider Network.
3	5	OUT	Regulator Output.
4	_	EP	Exposed Pad. Internally Connected to Ground.

4.0 APPLICATION INFORMATION

4.1 Enable/Shutdown

The MIC5233 comes with an active-high enable pin that allows the regulator to be disabled. Forcing the enable pin low disables the regulator and sends it into a "Zero" Off mode current state, consuming a typical 0.1 μ A. Forcing the enable pin high enables the output voltage.

4.2 Input Capacitor

The MIC5233 has a high input voltage capability, up to 36V. The input capacitor must be rated to sustain voltages that may be used on the input. An input capacitor may be required when the device is not near the source power supply or when supplied by a battery. Small surface mount, ceramic capacitors can be used for bypassing. A larger value may be required if the source supply has high ripple.

4.3 Output Capacitor

The MIC5233 requires an output capacitor for stability. The design requires 2.2 μ F or greater on the output to maintain stability. The design is optimized for use with low-ESR ceramic chip capacitors. High-ESR capacitors may cause high-frequency oscillation. The maximum recommended ESR is 3 Ω . The output capacitor can be increased without limit. Larger valued capacitors help to improve transient response.

X7R/X5R dielectric-type ceramic capacitors are recommended because of their temperature performance. X7R-type capacitors change capacitance by 15% over their operating temperature range and are the most stable type of ceramic capacitors. Z5U and Y5V dielectric capacitors change value by as much as 50% and 60%, respectively, over their operating temperature ranges. To use a ceramic chip capacitor with Y5V dielectric, the value must be much higher than an X7R ceramic capacitor to ensure the same minimum capacitance over the equivalent operating temperature range.

4.4 No-Load Stability

The MIC5233 will remain stable and in regulation with no load unlike many other voltage regulators. This is especially important in CMOS RAM keep-alive applications.

4.5 Thermal Consideration

The MIC5233 is designed to provide 100 mA of continuous current in a very small package. Maximum power dissipation can be calculated based on the output current and the voltage drop across the part.

To determine the maximum power dissipation of the package, use the junction-to-ambient thermal resistance of the device and Equation 4-1:

EQUATION 4-1:

$$P_{D(MAX)} = \left(\frac{T_{J(MAX)} - T_A}{\theta_{JA}}\right)$$

Where:

 $T_{J(MAX)}$ = Maximum junction temperature of the die at +125°C

 T_A = The ambient operating temperature

 θ_{JA} = Layout dependent

Table 4-1 shows examples of the junction-to-ambient thermal resistance for the MIC5233:

TABLE 4-1: 5-LEAD SOT23 AND SOT-223
THERMAL RESISTANCE

Package	θ _{JA} Recommended Minimum Footprint
SOT23-5	235°C/W
SOT223	50°C/W

The actual power dissipation of the regulator circuit can be determined using Equation 4-2:

EQUATION 4-2:

$$P_D \,=\, (V_{IN} - V_{OUT}) I_{OUT} + V_{IN} \times I_{GND}$$

Substituting $P_{D(MAX)}$ for P_D and solving for the operating conditions that are critical to the application will give the maximum operating conditions for the regulator circuit. For example, when operating the MIC5233-3.0YM5 at +50°C, with a minimum footprint layout, the maximum input voltage for a set output current can be determined as follows:

EQUATION 4-3:

$$P_{D(MAX)} = \left(\frac{125^{\circ}C - 50^{\circ}C}{235^{\circ}C/W}\right)$$

Where:

 $P_{D(max)} = 319 \text{ mW}$

The junction-to-ambient (θ_{JA}) thermal resistance for the minimum footprint is +235°C/W from Table 4-1. It is important that the maximum power dissipation not be exceeded to ensure proper operation. Because the MIC5233 was designed to operate with high input voltages, careful consideration must be given so as not to overheat the device. With very high input-to-output voltage differentials, the output current is limited by the total power dissipation.

Total power dissipation is calculated using the following equation:

EQUATION 4-4:

$$P_D = (V_{IN} - V_{OUT})I_{OUT} + V_{IN} \times I_{GND}$$

Due to the potential for input voltages up to 36V, ground current must be taken into consideration.

If we know the maximum load current, we can solve for the maximum input voltage using the maximum power dissipation calculated for a +50°C ambient, 319 mW.

EQUATION 4-5:

$$P_{D(MAX)} = (V_{IN} - V_{OUT})I_{OUT} + V_{IN} \times I_{GND}$$

$$319mW = (V_{IN} - 3V)100mA + V_{IN} \times 2.8mA$$

Ground pin current is estimated using the typical characteristics of the device.

EQUATION 4-6:

$$619mW = V_{IN}(102.8mA)$$

Where:

$$V_{IN} = 6.02V$$

For higher current outputs, only a lower input voltage will work for higher ambient temperatures.

Assuming a lower output current of 10 mA, the maximum input voltage can be recalculated:

EQUATION 4-7:

$$319mW = (V_{IN} - 3V)10mA + V_{IN} \times 0.1mA$$

 $349mW = V_{IN} \times 10.1mA$

Where:

$$V_{IN} = 34.55V$$

Maximum input voltage for a 10 mA load current at 50°C ambient temperature is 34.55V, utilizing virtually the entire operating voltage range of the device.

4.6 Adjustable Regulator Application

The MIC5233M5 can be adjusted from 1.24V to 20V by using two external resistors (Figure 4-1). The resistors set the output voltage based on the following equation:

EQUATION 4-8:

$$V_{OUT} = V_{REF} \bigg(1 + \bigg(\frac{R1}{R2} \bigg) \bigg)$$
 Where
$$V_{REF} = \ 1.24 V$$

Feedback resistor R2 should be no larger than 300 k Ω .

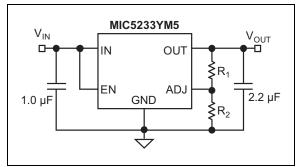


FIGURE 4-1: Adjustable Voltage Application.

5.0 PACKAGING INFORMATION

5.1 Package Marking Information

5-Lead SOT23* Example

TXXXX
XXXXNNNP

3-Lead SOT223* Example

XXXX

L350

Legend: XX...X Product code or customer-specific information
Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')
NNN Alphanumeric traceability code

(e3) Pb-free JEDEC® designator for Matte Tin (Sn)
* This package is Pb-free. The Pb-free JEDEC designator ((e3))
can be found on the outer packaging for this package.

•, ▲, ▼ Pin one index is identified by a dot, delta up, or delta down (triangle mark).

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.

Underbar (_) and/or Overbar (¯) symbol may not be to scale.

5-Lead SOT23 Package Outline and Recommended Land Pattern

TITLE 5 LEAD SOT23 PACKAGE OUTLINE & RECOMMENDED LAND PATTERN DRAWING # SOT23-5LD-PL-1 UNIT MM 2.90±0.10 0.95 TYP 10±0.20 **-**1.60±0.10-2.80±0.20 SEATING PLANE (MAX) 10° TYP (2 PLCS) 0.00 10° TYP (2 PLCS) SIDE VIEW TOP VIEW -1.90 BSC-0.95 BSC -0.45±0.1 2.60 ± 0.05 DETAIL .00±0.02 -0.66±0.02 END VIEW RECOMMENDED LAND PATTERN NOTE: NOTE: 1. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASH & BURR. 2. PACKAGE OUTLINE INCLUSIVE OF SOLER PLATING. 3. DIMENSION AND TOLERANCE PER ANSI Y14.5M, 1982. 4. FOOT LENGTH MEASUREMENT BASED ON GAUGE PLANE METHOD. 5. DIE FACES UP FOR MOLD, AND FACES DOWN FOR TRIM/FORM. 6. ALL DIMENSIONS ARE IN MILLIMETERS. For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging.

3-Lead SOT223 Package Outline and Recommended Land Pattern

TITLE 3 LEAD SOT223 PACKAGE OUTLINE & RECOMMENDED LAND PATTERN UNIT MM DRAWING # SOT223-3LD-PL-1 6.50±0.2 4,00±0,05 3.05±0.10 50,0±05 00±0 E 3,50±0,20 0.75±0.10 (3 PLCS) 50 ± 0.05 2.30±0.05 TOP VIEW 1.00±0.05 RECOMMENDED LAND PATTERN SIDE VIEW 8 13°±3° 0.06±0.04 SIDE VIEW NOTE: Dimensions and tolerances are as per ANSI Y14.5M, 1982. DETAILED VIEW 2. Controlling dimension: Millimeters. 3. Dimensions are exclusive of mold flash and gate burr. 4. All specification comply to Jedec spec T0261 Issue C. For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging.

APPENDIX A: REVISION HISTORY

Revision D (July 2019)

· Updated the Features section.

Revision C (February 2019)

- Information about the Automotive Grade option added in Features but removed from Package Types, and the Product Identification System sections of the data sheet.
- Updated the Typical Application Circuit on the very first page.

Revision B (June 2018)

- Unbolded values for V_{EN} in Table 1-1.
- The condition for Start-Up Time in the Electrical Characteristics table is updated.

Revision A (May 2018)

- Converted Micrel document MIC5233 to Microchip data sheet DS20006033A.
- · Minor text changes throughout.
- Information about the Automotive Grade option added in Features, Package Types, and the Product Identification System sections of the data sheet.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

DARTNO VV	v vvv vv	Examples:
PART NOX.X Device Outpu	t Junction Package Media Type	a) MIC5233-1.8YM5-TR: High Input Voltage, Low I _Ω μCap LDO Regulator, 1.8V, -40°C to +125°C, 5-Lead SOT23, 3000/Reel
Total	Range	b) MIC5233-2.5YM5-TR: High Input Voltage, Low I _Q µCap LDO Regulator, 2.5V, -40°C to +125°C, 5-Lead SOT23, 3000/Reel
Device:	MIC5233: High Input Voltage, Low I _Q μCap LDO Regulator	c) MIC5233-3.0YM5-TR: High Input Voltage, Low I _Q µCap LDO Regulator, 3.0V, -40°C to +125°C, 5-Lead SOT23, 3000/Reel
Output Voltage:	1.8 = 1.8V 2.5 = 2.5V	d) MIC5233-3.3YM5-TR: High Input Voltage, Low I _Q µCap LDO Regulator, 3.3V, -40°C to +125°C, 5-Lead SOT23, 3000/Reel
	3.0 = 3.0V 3.3 = 3.3V	e) MIC5233-5.0YM5-TR: High Input Voltage, Low I _Q µCap LDO Regulator, 5.0V, -40°C to +125°C, 5-Lead SOT23, 3000/Reel
	5.0 = 5.0V Adjustable Y = -40°C to +125°C	f) MIC5233YM5-TR: High Input Voltage, Low I _Q μCap LDO Regulator, Adjustable, –40°C to +125°C, 5-Lead SOT23, 3000/Reel
Junction Temperature Range:	Y = -40°C to +125°C	g) MIC5233-3.3YS: High Input Voltage, Low I _Q µCap LDO Regulator, 3.3V, -40°C to +125°C, 3-Lead SOT223, 78/Tube
Package:	M5 = 5-Lead SOT23 S = 3-Lead SOT223	h) MIC5233-5.0YS: High Input Voltage, Low I _Q µCap LDO Regulator, 5.0V, -40°C to +125°C, 3-Lead SOT223, 78/Tube
Media Type:	 TR = 2,500/Reel (SOT223 Only) TR = 3000/Reel (SOT23 Only)	i) MIC5233-5.0YS-TR: High Input Voltage, Low I _Q μCap LDO Regulator, 5.0V, -40°C to +125°C, 3-Lead SOT223, 2500/Reel
		Note: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

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